

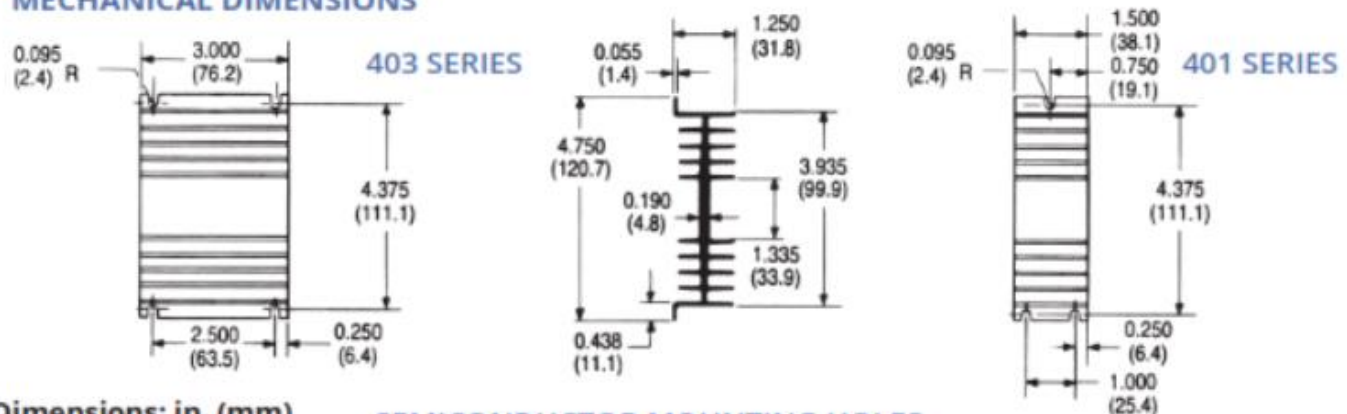


With fins oriented vertically in cabinet sidewall applications, **401 and 403 Series** heat sinks are recommended for critical space applications where maximum heat dissipation is required for high-power TO-3 case styles. Forced convection performance is also exemplary with these double surface fin types. Semiconductor mounting hole style "F" offers a single centered 0.270 in. (6.9)-diameter mounting hole (with a 0.750 in. (19.1)-diameter area free of anodize) for mounting stud-type diodes and rectifiers. Hole pattern "V" available upon request.

Standard P/N	Width in. (mm)	Overall Dimensions in. (mm)	Height in. (mm)	Semiconductor Mounting Hole Pattern	Thermal Performance at Typical Load		
					Natural Convection	Forced Convection	Weight lbs. (grams)
401A	4.750 (120.7)	1.500 (38.1)	1.250 (31.8)	(1) TO-3	80°C @ 30W	1.5°C/W @ 250 LFM	0.1500 (68.04)
401F	4.750 (120.7)	1.500 (38.1)	1.250 (31.8)	0.270 in. (6.9)-Dia Hole	80°C @ 30W	1.5°C/W @ 250 LFM	0.1500 (68.04)
401K	4.750 (120.7)	1.500 (38.1)	1.250 (31.8)	None	80°C @ 30W	1.5°C/W @ 250 LFM	0.1500 (68.04)
403A	4.750 (120.7)	3.000 (76.2)	1.250 (31.8)	(1) TO-3	55°C @ 30W	0.9°C/W @ 250 LFM	0.3500 (158.76)
403F	4.750 (120.7)	3.000 (76.2)	1.250 (31.8)	0.270 in. (6.9)-Dia Hole	55°C @ 30W	0.9°C/W @ 250 LFM	0.3500 (158.76)
403K	4.750 (120.7)	3.000 (76.2)	1.250 (31.8)	None	55°C @ 30W	0.9°C/W @ 250 LFM	0.3500 (158.76)

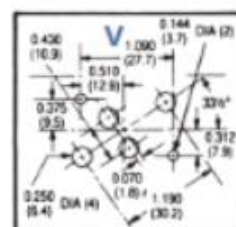
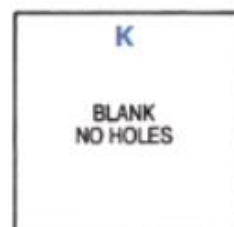
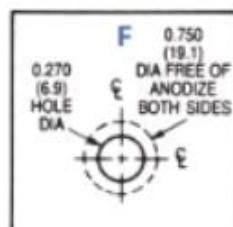
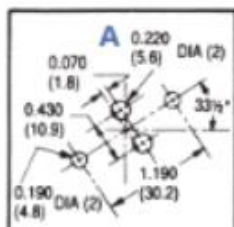
**Material:** Aluminum Alloy, Black Anodized.

### MECHANICAL DIMENSIONS



Dimensions: in. (mm)

### SEMICONDUCTOR MOUNTING HOLES



(EXTRUSION PROFILE 1024)

### NATURAL AND FORCED CONVECTION CHARACTERISTICS

